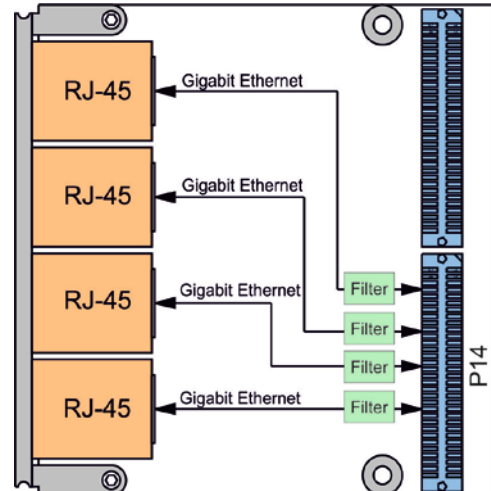
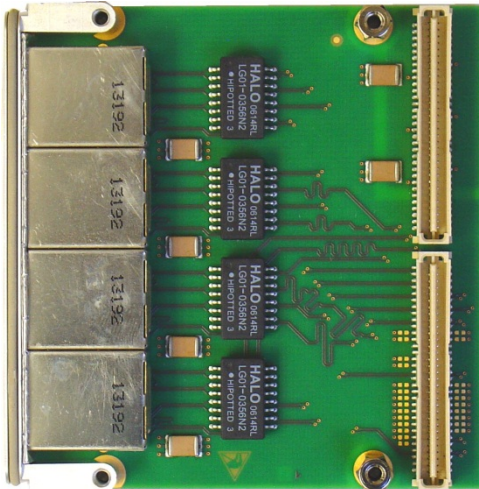


TPIM007 PIM I/O Module for Gigabit Ethernet XMCs



Application Information

The TPIM007 is a standard single-width PIM I/O module to be used on a PIM carrier. It offers easy access to the XMC back I/O lines of XMC carriers.

The TPIM007 distributes the Ethernet signals of TEWS' Gigabit Ethernet XMC modules with P16 back I/O to RJ-45 connectors located in the front panel of the PIM module.

Impedance mismatches, caused by CMC connectors and backplane connectors, lead to signal distortion of the Ethernet signals. To reduce these effects, the routing on the TPIM007 is optimized for differential Ethernet signals. Additionally, common mode choke filters are placed into the Ethernet signal lines to improve signal quality by suppressing common mode noise on the Ethernet signal lines.

The TPIM007-10R reproduces the front I/O signal mapping of TEWS four channel 10/100/1000Mbit/s Ethernet adapter XMC in its RJ-45 connectors when used with the TXMC385-10R for example.

The operating temperature is -40°C to +85°C.

Order Information

RoHS Compliant

TPIM007-10R PIM I/O Module for Quad 10/100/1000 Ethernet XMC

For the availability of non-RoHS compliant (lead solder) products please contact TEWS.

Documentation

TPIM007-DOC User Manual

Technical Information

- Form Factor: Standard single-width PIM I/O module conforming to VITA 36 – 199X Draft 0.1
 - Board size: 69 mm x 74 mm
- I/O lines routed to RJ45 connectors in the front panel
- EMI Front Panel
- Operating temperature: -40°C to +85°C
- MTBF (MIL-HDBK217F/FN2 GB 20°C)
TPIM007-10R: 667000 h